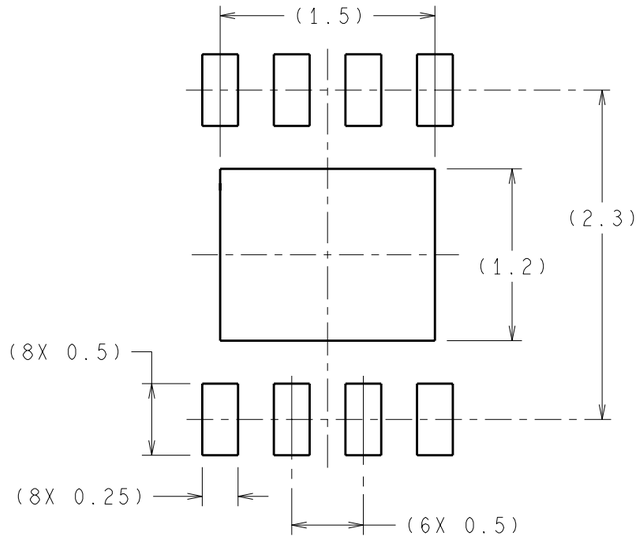
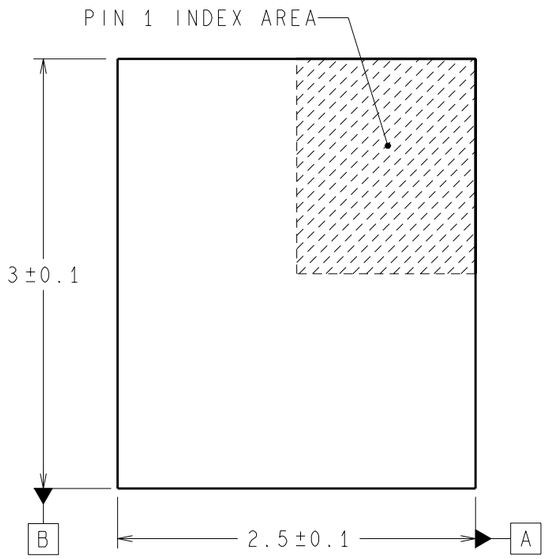
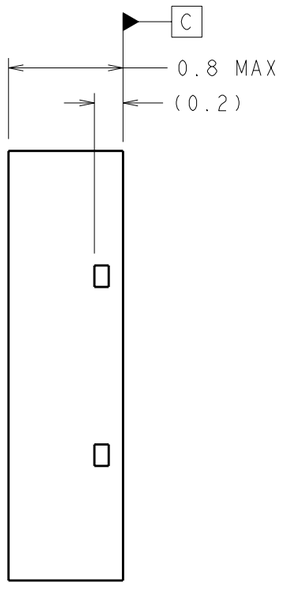
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12443	04/27/2000	SN/TL/AL
B	REPLACE NOTE 1 W/ SOLDER NOTE; ADD PIN 1 DIM'S; UPDATE DWG PER CURRENT STD; UPDATE JEDEC NOTE (2); CHANGE DWG FORMAT TO B SIZE	1095	06/25/2003	TL/RW

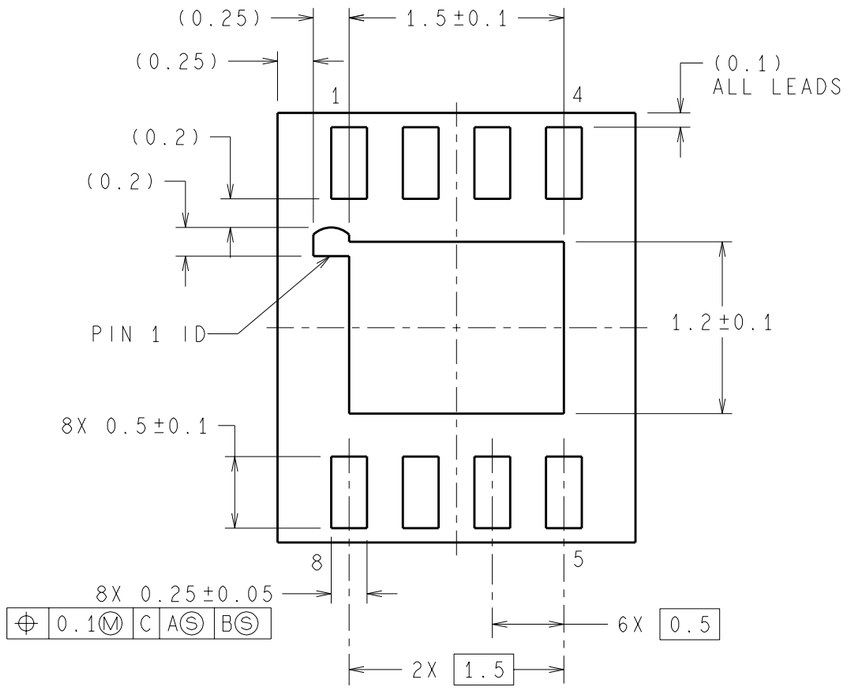


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY







NOTES: UNLESS OTHERWISE SPECIFIED.

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).

2. REFERENCE JEDEC REGISTRATION MO-229, VARIATION WDED.

APPROVALS	DATE
DRAWN N.SANTHIRAN & TL	12/06/2000
DFTG. CHK. MARTA SUCHY	06/25/2003
ENGR. CHK. RANDALL WALBERG	06/25/2003

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, DUAL, 2.5 X 3 X 0.75 mm BODY, 8 LD, 0.5 mm PITCH

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-LDA08C	B

FORMERLY: N/A | SHEET 1 of 1